



Texas Instruments licenses more Sonics intellectual property

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MOUNTAIN VIEW, Calif. -- Sonics Inc., a developer of on-chip interconnection architecture made available for license, said Monday (September 29, 2003) that Texas Instruments Inc. has agreed to license Sonics' SMART Interconnect IP for use in TI's OMAP chip designs for wireless, multimedia and other applications.

Sonics and Texas Instruments are already working together and both companies are board members of the Open Core Protocol International Partnership (OCP-IP) with which Smart Interconnect IP complies, Sonics said.

The agreement with Texas Instruments includes the Synapse 3220 peripheral interconnect IP and other interconnect under development at Sonics. The next products, covered by the agreement, are compatible with SiliconBackplane MicroNetwork IP interface and are being tailored for low-power operation, Sonics said.

Sonics also announced the introduction of a product it calls SiliconBackplane III Smart Interconnect.

"Sonics' Smart interconnect IP will be an important part of TI's wireless technology roadmap," said Yves Masse, chief OMAP architect and TI Fellow, in a statement issued by Sonics.

[Sonics](#) claims its approach to connecting logic blocks on a chip is silicon efficient and has high data throughput.

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